

LoRaWAN Module

ME25LS01



Datasheet

V 1.0.0



ME25LS01-LR1110+nRF52840

High-performance, long-range, small-size, ultra-low-power, supports WiFi-scan/GNSS/BLE/LoRaWAN multi-protocol

The ME25LS01 is a highly-performance, long-range, ultra-low power, Small size, support WiFi-scan/GNSS(G-PS/BDS)/BLE5.3/LoRaWAN and other multi-protocols, and has a large storage capacity of 256KB RAM and 1MB Flash. The ME25LS01 has better reception sensitivity, with BLE as low as -96dBm and LoRa as low as -125.6dBm, and , the maximum power of BLE is 6dBm and the maximum power of LoRa is 22dBm, which is available for longer transmission distances. the power supply voltage of the module is 3.3V, and there are abundant GPIOs. and has a completely open-source development platform, which supports customers' secondary development and customisation needs.

FEATURES



Cortex M4 high performance MCU



Low power, dual low power chip combination



BLE 5.3, supports BLE long-range



Abundant IO ports, USB, Uart, I2C, etc



Open-source development platform

KEY PARAMETER

ME25LS01			
Chip Model	LR1110+nRF52840	Antenna	ANT pin
Module Size	25.5x20x2.6mm	GPIO	44
Flash	1MB	RAM	256KB
Receiving Sensitivity	BLE: -96dBm LoRa: -125.6dBm	Transmission Power	BLE:-40~+8dBm LoRa: 22dBm
Current(TX)	Max- 118mA	Current(RX)	Max-10.7mA

APPLICATION



Agricultural automation



Asset tracking



Inventory management



Livestock tracking

COPYRIGHT STATEMENT

This manual and all the contents contained in it are owned by Shenzhen Minewsemi Co., Ltd. and are protected by Chinese laws and applicable international conventions related to copyright laws.

The certified trademarks included in this product and related documents have been licensed for use by MinewSemi. This includes but is not limited to certifications such as BQB, RoHS, REACH, CE, FCC, BQB, IC, SRRC, TELEC, WPC, RCM, WEEE, etc. The respective textual trademarks and logos belong to their respective owners. For example, the Bluetooth® textual trademark and logo are owned by Bluetooth SIG, Inc. Other trademarks and trade names are those of their respective owners. Due to the small size of the module product, the "®" symbol is omitted from the Bluetooth Primary Trademarks information in compliance with regulations.

The company has the right to change the content of this manual according to the technological development, and the revised version will not be notified otherwise. Without the written permission and authorization of the company, any individual, company, or organization shall not modify the contents of this manual or use part or all of the contents of this manual in other ways. Violators will be held accountable in accordance with the law.

RELATED DOCUMENTS

- LR1110_Chip_Datasheet
https://en.minewsemi.com/file/LR1110_Chip_Datasheet_EN.pdf
- nRF52840_Chip_Datasheet
https://en.minewsemi.com/file/nRF52840_Chip_Datasheet_EN.pdf
- MinewSemi_Product_Naming_Reference_Manual_V1.0
https://en.minewsemi.com/file/MinewSemi_Product_Naming_Reference_Manual_EN.pdf
- MinewSemi_Connectivity_Module_Catalogue_V2.0
https://en.minewsemi.com/file/MinewSemi_Connectivity_Module_Catalogue_EN.pdf



For product change notifications and regular updates of Minewsemi documentation, please register on our website: www.minewsemi.com

MINESEMI

SHENZHEN MINEWSEMI CO., LTD.



0086-755-2801 0353

<https://minewsemi.com>minewsemi@minew.com<https://store.minewsemi.com>

No.8, Qinglong Road, Longhua District, Shenzhen, China